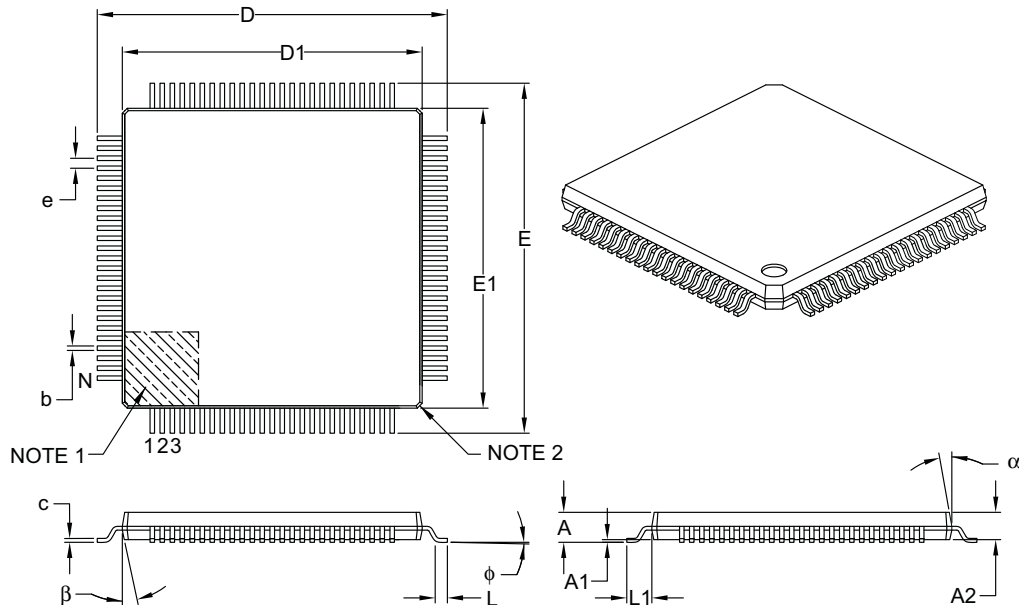


100-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Leads	N		100		
Lead Pitch	e		0.40 BSC		
Overall Height	A		–	–	1.20
Molded Package Thickness	A2		0.95	1.00	1.05
Standoff	A1		0.05	–	0.15
Foot Length	L		0.45	0.60	0.75
Footprint	L1		1.00 REF		
Foot Angle	φ		0°	3.5°	7°
Overall Width	E		14.00 BSC		
Overall Length	D		14.00 BSC		
Molded Package Width	E1		12.00 BSC		
Molded Package Length	D1		12.00 BSC		
Lead Thickness	c		0.09	–	0.20
Lead Width	b		0.13	0.18	0.23
Mold Draft Angle Top	α		11°	12°	13°
Mold Draft Angle Bottom	β		11°	12°	13°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Chamfers at corners are optional; size may vary.
- Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

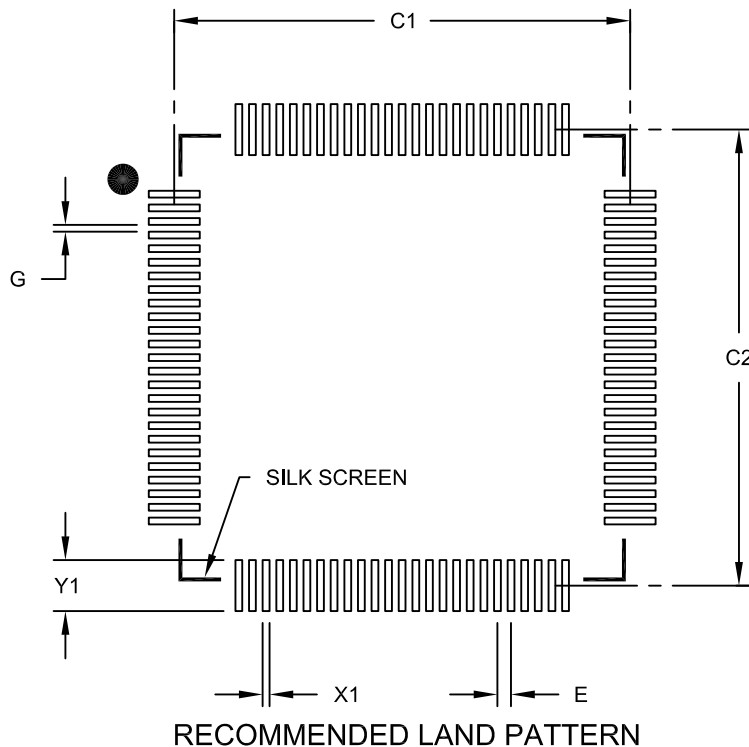
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-100B

100-Lead Plastic Thin Quad Flatpack (PT)-12x12x1mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X100)	X1			0.20
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2100B

